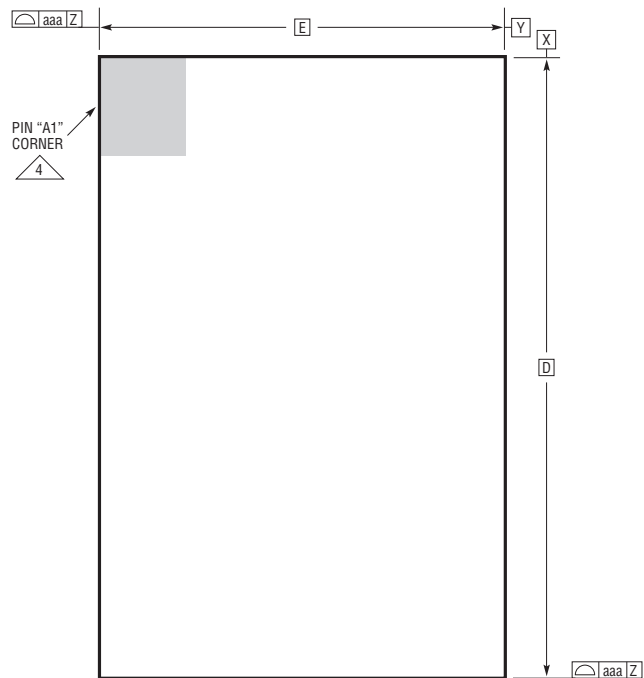
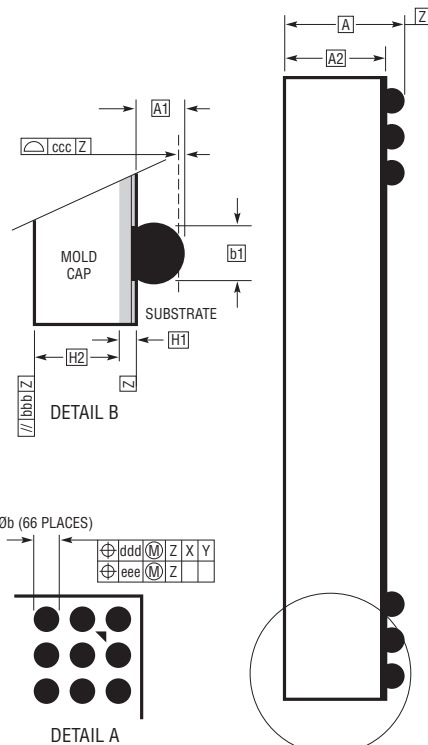


**BGA Package**  
**66-Lead (22mm × 15mm × 5.16mm)**  
 (Reference LTC DWG# 05-08-1972 Rev 0)

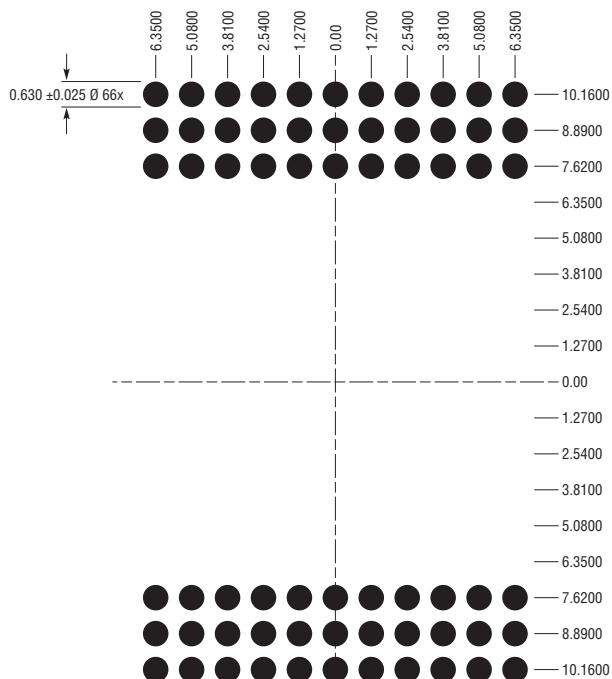


PACKAGE TOP VIEW



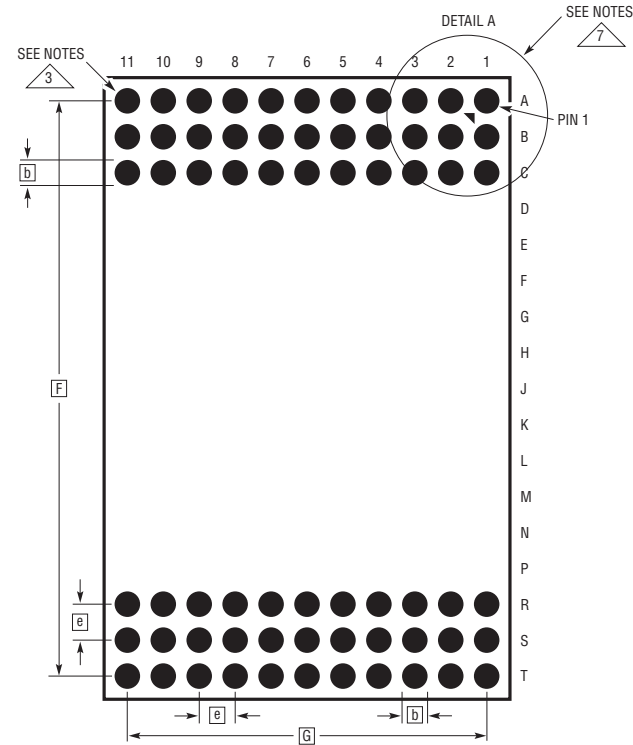
DETAIL A

DETAIL B  
PACKAGE SIDE VIEW



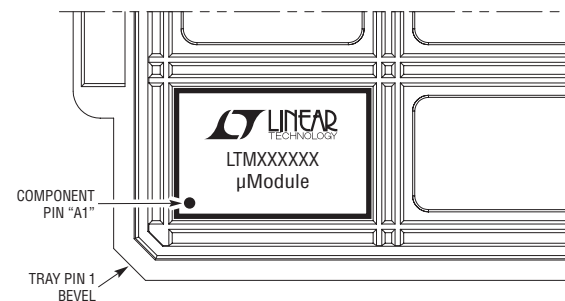
SUGGESTED PCB LAYOUT  
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.91	5.16	5.41	
A1	0.50	0.60	0.70	
A2	4.41	4.56	4.71	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D		22.00		
E		15.00		
e		1.27		
F		20.32		
G		12.70		
H1	0.46	0.56	0.66	
H2	3.95	4.00	4.05	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 66				



PACKAGE BOTTOM VIEW

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
  2. ALL DIMENSIONS ARE IN MILLIMETERS
  3. BALL DESIGNATION PER JESD MS-028 AND JEP95
  4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
  5. PRIMARY DATUM -Z- IS SEATING PLANE
  6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu
  7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION